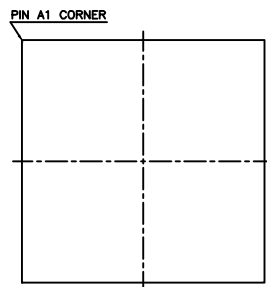
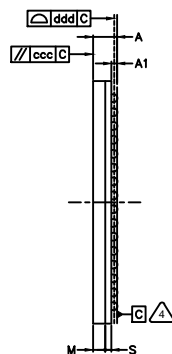


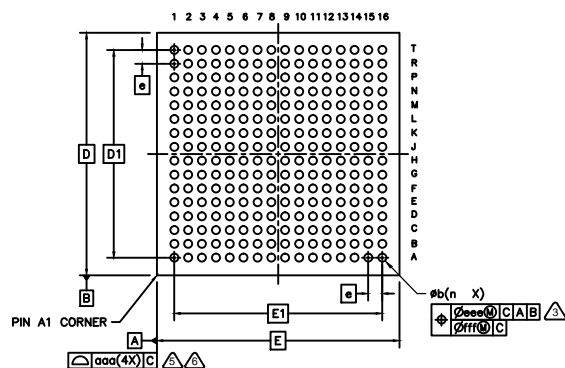
TOP VIEW



SIDE VIEW



		Symbol	Common Dimensions		
			MIN.	NOM.	MAX.
Body Size:	X	E	14.000		
	Y	D	14.000		
Ball Pitch :		e	0.800		
Total Thickness :		A	—	—	1.700
Mold Thickness :		M	0.700		Ref.
Substrate Thickness :		S	0.360		Ref.
Ball Diameter :			0.450		
Stand Off :	A1	0.250	—	0.400	
Ball Width :	b	0.400	0.450	0.500	
Package Edge Tolerance :		aaa	0.150		
Mold Parallelism :		ccc	0.200		
Coplanarity:		ddd	0.200		
Ball Offset (Package) :		eee	0.150		
Ball Offset (Ball) :		fff	0.080		
Ball Count :		n	256		
Edge Ball Center to Center :	X	E1	12.000		
	Y	D1	12.000		



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.
3. DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.
4. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.
6. EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.
7. JEDEC REFERENCE: MO-275. VARIATION JJAB-2

BOTTOM VIEW

Title: Package Outline Drawing	Pkg Type: CABGA	Document No:	POD-250078
Product Family: LFMXO4	Pin Count: 256		
Product Name: LFMXO4-015/025/050/080/110-BBG256	Pkg Size: 14x14 mm	Rev: A	
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